



<b>Title of Change:</b>	Update Notice to FPCN21818X - NCL30002DR2G will no longer be affected by the previously announced FPCN21818X.	
<b>Proposed first ship date:</b>	19 December 2017 or earlier upon customer approval	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Jack.Cartwright@onsemi.com>	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Phine.Guevarra@onsemi.com>	
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
<b>Change Part Identification:</b>	Affected products will be identified with assembly site trace code to "AK".	
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
<b>Sites Affected:</b>	ON Semiconductor Sites: None	External Foundry/Subcon Sites: ASE Kunshan
<b>Description and Purpose:</b>		
<p>This is an Update Notice to FPCN21818X to announce that NCL30002DR2G will no longer be affected by previously released notification.</p> <p>FPCN21818X was previously issued on August 4 2017 announcing the qualification of Advance Semiconductor Engineering Kunshan (ASEKS) as an alternative site for assembly and test to increase capacity of SOIC8 devices with changes on the following:</p>		
	<b>Before Change Description</b>	<b>After Change Description</b>
Leadframe	Ag Spotted lead frame 65 x 65 mils	Ag Spotted lead frame 70 x 73.4 mils
Mold Compound	G600	CEL9240
Die Attach	CRM-1076WB	EN4900
<b>Electrical Characteristic Summary:</b>		
Electrical characteristics are not impacted.		
<b>List of Affected Part:</b>		
<b>Part Number</b>	<b>Qualification Vehicle</b>	
NCL30002DR2G	NCP1252ADR2G NCP1607BDR2G NCP1608BDR2G	